

What is claimed is:

1. A package for containing semiconductor element comprising:

a package having a recess portion for containing a semiconductor element; and

a pair of positioning holes and a pair of attaching holes respectively provided at a pair of opposed side portions of said recess portion at a surface of said package,

wherein a line connecting said pair of positioning holes and a line connecting said pair of attaching holes are intersected with each other substantially at a center of said package.

2. The package according to claim 1:

wherein said semiconductor element is a solid-state imaging element.

3. A semiconductor device comprising:

a semiconductor element;

a package having a recess portion for containing said semiconductor element; and

a pair of positioning holes and a pair of attaching holes respectively provided at a pair of opposed side portions of said recess portion at a surface of said package;

wherein a line connecting the pair of positioning holes

and a line connecting said pair of attaching holes are intersected with each other substantially at a center of said package.

4. The semiconductor device according to claim 3, wherein said semiconductor element is a solid-state imaging element.

5. A semiconductor device comprising:
a semiconductor element;
a package having a recess portion for containing said semiconductor element;

a pair of attaching holes provided at a pair of opposed side portions of said recess portion at a surface of said package; and

a transparent member for sealing said semiconductor element in said recess portion;

wherein said surface of said package is made to be higher than a top surface of said transparent member.

6. The semiconductor device according to claim 5, wherein said semiconductor element is a solid-state imaging element.